

## UNIVERSAL INSTRUMENTS NEWS RELEASE

For Immediate Release: August 28, 2024

-----

### Universal Instruments Joins Parent Company Delta to Highlight Comprehensive Semiconductor Solutions at SEMICON Taiwan

#### Transformative equipment, software and cybersecurity solutions poised for new semiconductor era

Universal Instruments will join parent company Delta, a global leader in power and thermal management technologies and a world-class provider of industrial automation solutions, on booth S7542 at the SEMICON Taiwan trade show on September 4–6. The booth will feature a seamless integration of semiconductor solutions, including Delta’s Wafer Edge Profile Measurement Machine for front-end processing and Universal’s FuzionSC™ and High-Speed Wafer Feeder back-end multi-die placement solution. Delta will also showcase its Digital-Twin (DIA-Twin) simulation software and adoption of the SEMI E187 cybersecurity practices, surpassing current industry standards.

The Wafer Edge Profile Measurement Machine measures the notch, flat length and edge shape of the ground wafer while also detecting wafer quality and defects. It employs non-destructive AOI optical technology to take these measurements with micro-scale repeatability, which achieves a high throughput of approximately 60-120 wafers per hour. The system supports automated robotic loading/unloading and AGV transport systems, combining diverse functions into a single machine. Delta also offers additional front-end processing solutions including Wafer Edge Grinding, Sorting and IR Pinhole Inspection.

DIATwin is an intelligent design and development tool that can precisely simulate loading points and paths in a virtual environment, enabling the evaluation of production cycle times and reducing the trial-and-error costs in new product introduction. Integrating the DIATwin Virtual Machine Development Platform with front-end equipment to create virtual environments greatly improves efficiency of new product introductions.

The FuzionSC Platform combined with the HSWF is the ultimate solution for challenging multi-die package applications. It’s capable of placing passives and multiple die types in a single cell, eliminating the need to move product between cells and maximizing accuracy and efficiency.

Customer Support Center  
T: +1 800 842 9732 or  
T: +1 607 779 5000

AMERICAS  
T: +1 800 432 2607 or  
T: +1 607 779 7522

CHINA, SHENZHEN  
T: +86 755 2685 9108  
CHINA, SHANGHAI  
T: +86 21 6495 2100

PENANG, MALAYSIA  
T: +60 4 644 7067  
EUROPE  
T: +421 2 4930 96 60

[www.uic.com](http://www.uic.com)  
email: [universal@uic.com](mailto:universal@uic.com)

Universal Instruments Vice President of Global Customer Operations and Corporate Marketing, Glenn Farris stated, “The complementary semiconductor solutions we’re able to offer put our customers at the forefront of this fast-moving target. Tying front-end and back-end equipment and processes together, leveraging AI and digital twin technologies to streamline NPI and production, and protecting assets with advanced cybersecurity are all integral advantages.”

Along with visiting the booth, Universal encourages attendees to join a technical presentation by Universal Instruments VP of Global Customer Operations and Corporate Marketing, Glenn Farris. On Friday, September 6 at 11:20 am CST at the HITECH Smart Manufacturing Forum he will present “Accelerating Innovation: Smart Manufacturing for Advanced Semiconductor Packaging”.

To learn more about Universal’s solutions for any electronics manufacturing challenge, contact Universal Instruments at +1-800-432-2607 or +1-607-779-7522 or visit [www.uic.com](http://www.uic.com).

### **About Universal Instruments**

Universal Instruments, a Delta Group Company, is a global leader in the design and manufacture of advanced automation and assembly equipment solutions for the electronics manufacturing industry. Universal Instruments delivers comprehensive solutions to a global customer base by leveraging exclusive process expertise combined with its innovative portfolio of flexible platforms for surface mount, insertion mount, advanced semiconductor packaging, and end-of-line automation. Universal Instruments is headquartered in Conklin, N.Y., USA, with offices in Europe, Asia and the Americas.

<b>Universal Instruments contact</b>
<b>Jeffrey Zopff</b> Manager, Corporate Branding & Design Universal Instruments Corporation 33 Broome Corporate Parkway Conklin, NY 13748 USA
Tel: +1 607.779.5364 Email: <a href="mailto:zopff@uic.com">zopff@uic.com</a> <a href="http://www.uic.com">www.uic.com</a>